



## Customized Adhesive Solutions

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# NGAC P907-30 MOD1

# Technical Bulletin

## Low Shrinkage and Controlled Flow Adhesive

### Description:

NGAC P907-30 MOD1 is a high viscosity, controlled flow encapsulant designed for microelectronics applications requiring low shrinkage and high reliability performance.

### Advantages and Applications:

Uses include protecting wire bonds and bare die and other micro-electronic structural assembly applications. NGAC P907-30 MOD1 has a low CTE resulting in low shrinkage upon cure and no stress to substrates. It is highly resistant to humidity and will withstand reflow temperatures up to 260C.

NGAC P907-30 MOD1 features the following characteristics that enable ease of use.

### Storage Requirements:

NGAC P907-30 MOD1 is packaged in pre-mixed and frozen syringe. It must be shipped in dry ice and stored in a freezer at -40C or colder.

Shelf life of each lot will be exactly 6 months from date of manufacture with storage at -40C Minimum.

### Properties:

	Typical Value
Color	Black
Specific Gravity	1.80
Hardness Shore D	95D
Operating Temperature:	-40 to 260°C
Glass Transition Temperature	120°C
Working Life***	24h

### Cure Schedule:

Temperature	100°C	<b>PLUS</b>	150°C
Time	30 minutes		45 minutes

**OR**

Temperature	150°C
Time	45 minutes

\*\*\*Working life is subjective to application requirements.

For additional information or assistance, please call  
**978-436-9600**

All values reported above are typical values and are for reference use only. These values are not intended for use in developing specifications. Application testing under specific conditions should be performed to determine actual results and fitness for use.